



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TECHNOLOGY CENTER 2800
OCT -3 2002
REF ID: A6010102

#16
Amndt
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10/10/02
OCT -3 2002

In re the Application of:

Donald C. Abbott
Serial No.: CPA of 09/525,105
Filed: Herewith
For: Semiconductor Circuit Assembly Having a Plated Leadframe Including Gold Selectively Covering Areas to be Soldered (As Amended)

Docket No.: TI-28098
Examiner: TBD
Art Unit: TBD

Preliminary Amendment

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to:
Assistant Commissioner for Patents, Washington, D.C. 20231 on

9-27-02

Marianna Smith
Marianna Smith

Dear Sir:

Please enter the following amendments prior to examination of the instant application.

In the Claims:

- 10/11/2002 AJENKINS: 00000002, 200668 09525105
01 TC 102 168.00 CH
1. (amended) A leadframe for use with packaged integrated circuit chips comprising:
gold selectively plated on segments of said leadframe intended for solder attachment.
 2. (amended) A leadframe for use with packaged integrated circuit chips, having a chip mount pad and a plurality of lead segments, comprising:
 - a leadframe base made of copper or copper alloy;
 - a first layer of nickel deposited on said copper or copper alloy;
 - a layer of an alloy of nickel and palladium on said first nickel layer;